REMARKS/ARGUMENTS

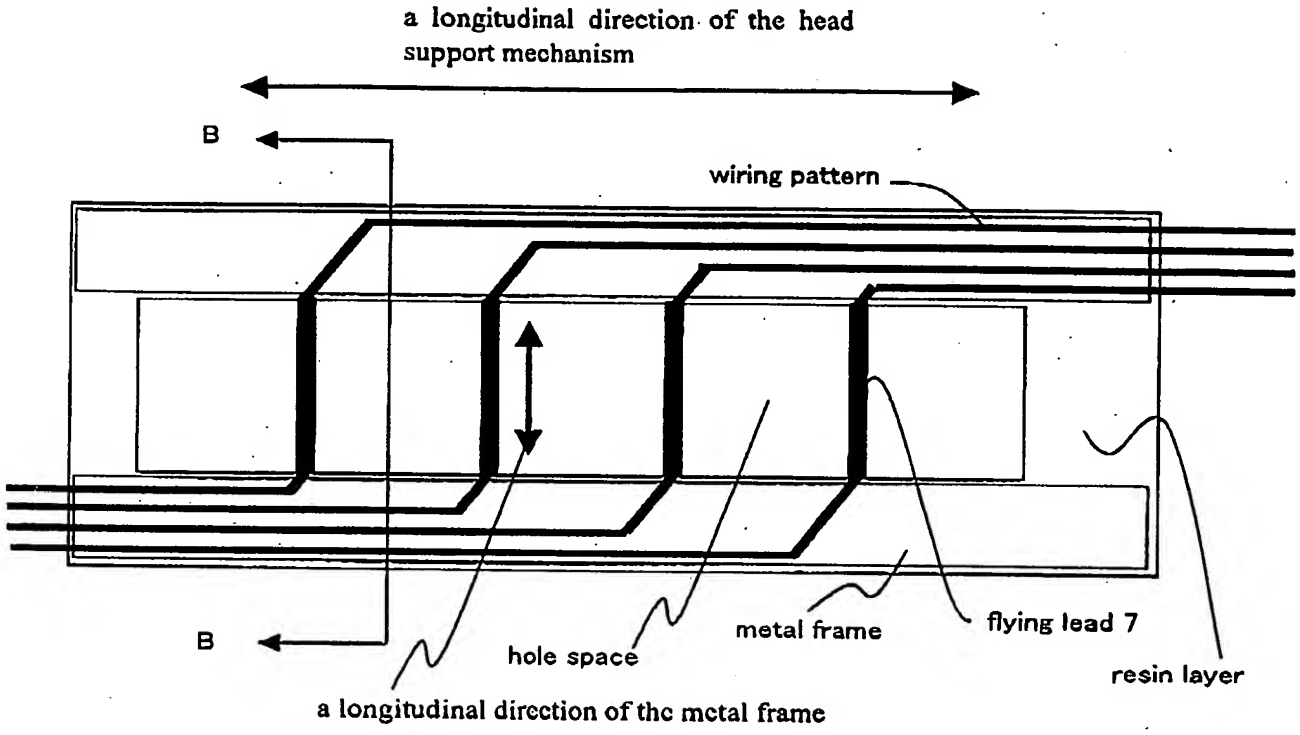
Claims 1-20 are pending. Claims 1-5 have been amended. New claims 6-20 have been added. No new matter has been introduced. Applicants believe the claims comply with 35 U.S.C. § 112.

Claims 1-5 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Okamoto et al. (US 6,731,472) in view of JP 10-092126 and Inaba (US 5,844,753).

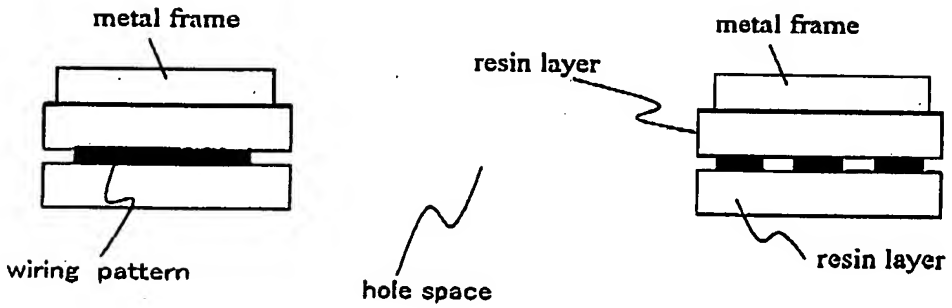
Applicants respectfully submit that independent claims 1, 2, 4, and 5 are patentable over Okamoto et al., JP 10-092126, and Inaba because, for instance, they do not teach or suggest that the plural flying lead members of the flying lead are spaced from each other by open spaces in a longitudinal direction of the head support mechanism, and one side of the resin layer covering the wiring pattern is supported by a metal frame formed in a longitudinal direction of the head support mechanism, electrically insulated from the flying lead and the wiring pattern.

The metal frame serves as a framework for reinforcing the flying lead. The claimed features are shown in Figs. 1, 2, and 4 and described in paragraph [0020] of the present application. The following reference figures more clearly illustrate the claimed features. Reference Fig. 1 is an enlarged view of the flying lead 7 of Fig. 1 of the present application, while Reference Fig. 2 is a B-B cross-sectional view of Reference Fig. 1. In the embodiment shown, the longitudinal direction of the head 1 support mechanism is perpendicular to the longitudinal direction of the metal frame 14. The flying lead members of the flying lead 7 are spaced from each other by open spaces. The metal frame 14 supports one side of the resin layer, and is formed in the longitudinal direction of the head support mechanism 1. The metal frame 14 reinforces the flying lead 7.

Reference Fig.1 (Enlarged view of flying lead 7 part of Fig.1)



Reference Fig.2 (B-B cross-section view of Reference Fig.1. cf. Fig. 4)



In contrast, Okamoto et al. discloses bonding wire 80, flying lead 81, and conductive member 82 (see Figs. 11-13). The flying lead 81 is connected to the actuator member 30. As such, there is no need and no motivation to provide reinforcement (e.g., a metal frame) near the flying lead 81. Okamoto et al. does not show the arrangement of the flying lead and the metal frame supporting one side of the resin layer covering the wiring pattern as claimed.

JP 10-092126 discloses a relay board 70 having plural relay pads 76 on the bridge 83 that are set in array in a longitudinal direction of the head support mechanism (see Fig. 7). The relay pads 76 are not flying leads, however, since the relay pads 76 are disposed on the bridge 83 of the relay board 70. Usually, the rigidity of the relay board is enough to set to HSA easily. Again, there is no need and no motivation to provide reinforcement (e.g., a metal frame) on the relay board 70. JP 10-092126 also fails to show the arrangement of the flying lead and the metal frame supporting one side of the resin layer covering the wiring pattern as claimed.

Inaba discloses a springy metal layer 2. According to the clamping force of the springy metal layer 2, the magnet head junction board 8 is connected to the magnetic head suspension 10. The Examiner alleges that the springy metal layer 2 is the claimed metal frame. The springy metal layer 2, however, wraps around the wiring patterns 3 in a direction transverse to the magnetic head junction board 8 and the magnetic head suspension 10. Inaba does not show plural flying lead members of the flying lead spaced from each other by open spaces in a longitudinal direction of the head support mechanism. Nor does Inaba show a metal frame formed in a longitudinal direction of the head support mechanism and supporting one side of the resin layer covering the wiring patterns. Therefore, Inaba also fails to show the arrangement of the flying lead and the metal frame supporting one side of the resin layer covering the wiring pattern as claimed.

For at least the foregoing reasons, independent claims 1, 2, 4, and 5, and claims 3 and 6-20 depending therefrom, are patentable.

CONCLUSION

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 650-326-2400.

Respectfully submitted,

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